

What is claimed is:

1. A stack type multi-chip package comprising:

a first semiconductor chip which shows good results when tested for reliability after being assembled at a package level;

5 at least one second semiconductor chip which is in a wafer level configuration and is stacked on the first semiconductor chip via stacking means;

a first connecting unit for electrically connecting the first semiconductor chip to an external system; and

10 a second connecting unit for electrically connecting the second semiconductor chip to the external system,

wherein the first connecting unit is different from the second connecting unit.

2. The stack type multi-chip package of claim 1, further comprising a printed circuit board for the multi-chip package, which includes bonding pads to which the first  
15 connecting unit and the second connecting unit are connected, and pins for connecting the bonding pads to the external system.

3. The stack type multi-chip package of claim 2, further comprising a molding compound for fastening the first and second semiconductor chips and protecting the  
20 first and second semiconductor chips from the external environment.

4. The stack type multi-chip package of claim 3, wherein the stacking means are an adhesive.

25 5. The stack type multi-chip package of claim 4, wherein the package type of the first semiconductor chip is a Fine Ball Grid Array (FBGA) or a Wafer-Level Chip Size Package (W-CSP).

30 6. The stack type multi-chip package of claim 5, wherein the first connecting unit is a solder bump for connecting solder balls of the FBGA or the W-CSP to the bonding pads of the printed circuit board,

the second connecting unit is bonding wires for connecting pads of the second semiconductor chip to the bonding pads of the printed circuit board.

7. The stack type multi-chip package of claim 6, wherein the package type of the printed circuit board is a Ball Grid Array (BGA).

8. The stack type multi-chip package of claim 7, wherein the first semiconductor chip and the second semiconductor chip are stacked via the adhesive such that their back surfaces face each other.

9. The stack type multi-chip package of claim 4, wherein the package type of the first semiconductor chip is a Thin Quad Flat package (TQFP) or a Super Thin Small Outline Package (STSOP).

10. The stack type multi-chip package of claim 9, wherein the first connecting unit is a solder bump for connecting pins of the TQFP or the STSOP to the bonding pads of the printed circuit board,

the second connecting unit is bonding wires for connecting pads of the second semiconductor chip to the bonding pads of the printed circuit board.

11. The stack type multi-chip package of claim 10, wherein the package type of the printed circuit board is a BGA.

12. The stack type multi-chip package of claim 10, wherein the package type of the printed circuit board is a TQFP.

13. The stack type multi-chip package of claim 11, wherein one surface, on which pads of the first semiconductor chip are disposed, faces and is stacked on a back surface of the second semiconductor chip via the adhesive.

14. The stack type multi-chip package of claim 12, wherein one surface, on which pads of the first semiconductor chip are disposed, faces and is stacked on a back surface of the second semiconductor chip via the adhesive.

5 15. The stack type multi-chip package of claim 4, wherein the package type of the first semiconductor chip is a BGA.

10 16. The stack type multi-chip package of claim 15, wherein the first connecting unit is a solder bump for connecting solder balls of the BGA to the bonding pads of the printed circuit board,

the second connecting unit is bonding wires for connecting pads of the second semiconductor chip to the bonding pads of the printed circuit board.

15 17. The stack type multi-chip package of claim 16, wherein the package type of the printed circuit board is a TQFP.

20 18. The stack type multi-chip package of claim 17, wherein the first semiconductor chip and the second semiconductor chip are stacked via the adhesive such that their back surfaces face each other.